

ABSTRACT OF THE DISCLOSURE

A method and apparatus for conditioning a polishing pad is described. The method includes applying a stream of pressurized liquid to the polishing pad, and removing a significant amount of slurry and liquid from the polishing pad using a vacuum. The apparatus includes a liquid distribution unit forming at least one opening upon which liquid is forced through at high pressure, the opening directed at the polishing pad, and a liquid recovery unit positioned downstream from the liquid distribution unit and in communication with the polishing pad, the liquid recovery unit connected with a vacuum for removing liquid and slurry from the polishing pad.